



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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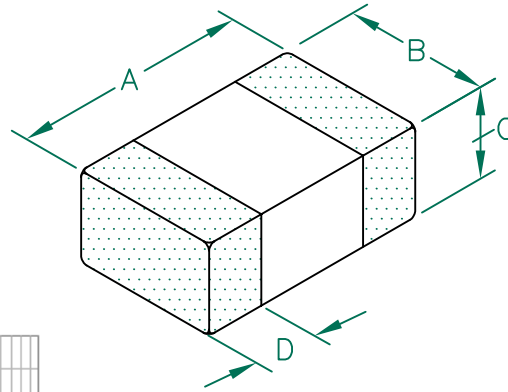


CPI0805IR82R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00 [.079]	\pm	0.20[.008]
B	1.25 [.049]	\pm	0.20[.008]
C	0.90 [.035]	\pm	0.10[.004]
D	0.50 [.020]	\pm	0.20[.008]



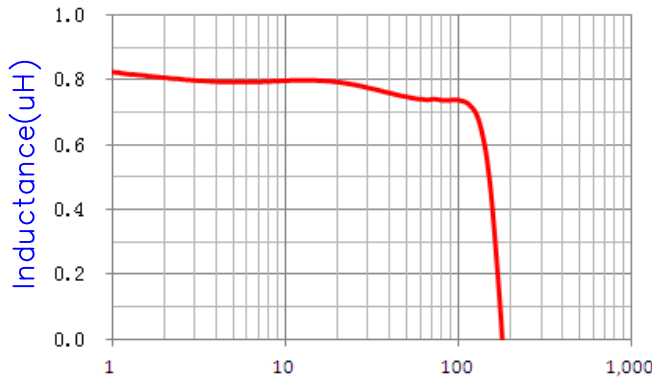
ELECTRICAL CHARACTERISTICS:

	L (μ H) @ 1MHz \pm 20%	DCR (Ω) \pm 25%	I (Max)
Nom	0.82	0.14	
Min	0.66	0.105	
Max	0.98	0.175	900mA

NOTES: UNLESS OTHERWISE SPECIFIED

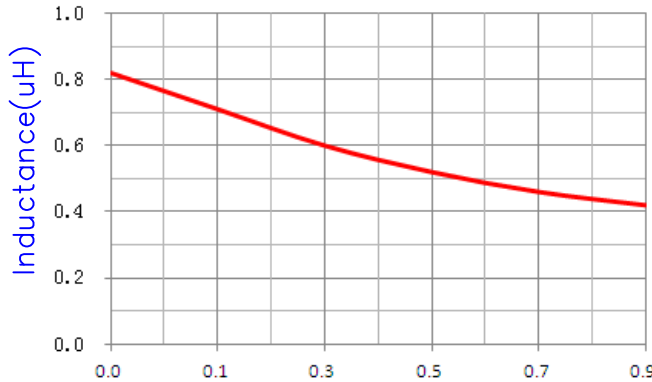
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

Ls vs Frequency



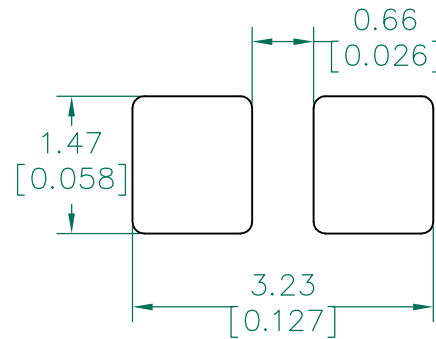
Frequency (MHz)

Ls vs DC BIAS Current



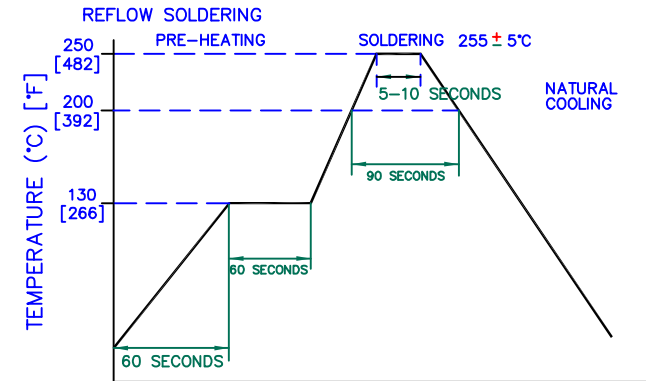
DC BIAS Current (A)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
PROJECT/PART NUMBER:				REV	PART TYPE:	DRAWN BY:	
CPI0805IR82R-10				C	CO-FIRE	QU	
DATE:				SCALE:		SHEET:	
03/01/11				NTS		1 of 1	
REV	DESCRIPTION	DATE	INT	CAD #	TOOL #		
A	ORIGINAL DRAFT	03/01/11	QU				
B	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU				
C	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU				

